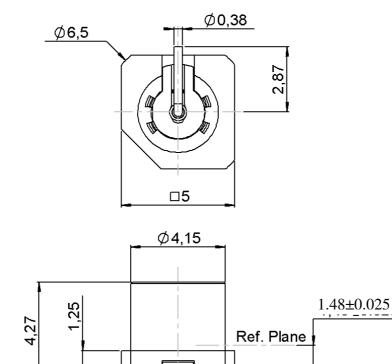
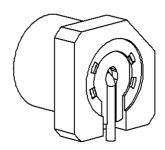
# R222.941.100

## **FULL DETENT-TAPE AND REEL BY 500**

Series : **SMP-COM** 







All dimensions are in mm.

COMPONENTS MATERIALS PLATING (μm)		7	
	COMPONENTS	PLATING (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS		

**Issue:** 1121 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



# R222.941.100

### **FULL DETENT-TAPE AND REEL BY 500**

Series: SMP-COM

## **PACKAGING**

Standard	Unit	Other	
500		Contact us	

## **SPECIFICATION**

# **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-12.4*} \;\; \text{GHz} \end{array}$ 

VSWR 1.1\*\* + 0,0000 x F(GHz) Maxi

Insertion loss  $0.12 \sqrt{F(GHz)} dB Maxi$  RF leakage -(NA - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 M $\Omega$  mini

# **ENVIRONMENTAL**

Operating temperature -55/+125 ° C

Hermetic seal NA Atm.cm3/s
Panel leakage NA

# OTHER CHARACTERISTICS

Assembly instruction NA

Others:

\* ROS 1.35 at 12.4GHz

\*\*ROS at 6GHz

# **MECHANICAL CHARACTERISTICS**

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3350** g

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RADIALL®

**FULL DETENT-TAPE AND REEL BY 500** 

# R222.941.100

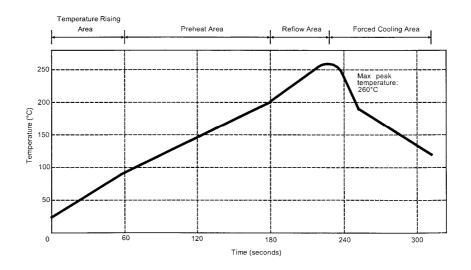
Series: SMP-COM

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

**SOLDER PROCEDURE** 

- We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

# **TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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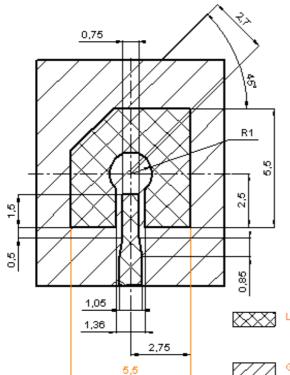


# R222.941.100

Series: SMP-COM

# **FULL DETENT-TAPE AND REEL BY 500**

# STANDARD PAD(For ROGERS 4350)



## **COPLANAR LINE**

Pattern and signal are on the same side.

Thickness of PCB: 1.6mm

The material of PCB is the epoxy resin of

glass fabrics bacs (ER:4.8).

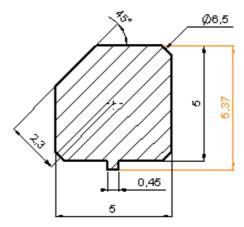
The solder resist should be printed exept for

the land pattern on the PCB.

Lands for solder paste

Ground + Varnish

# SHADOW OF RECEPTACLE FOR VIDEO CAMERA



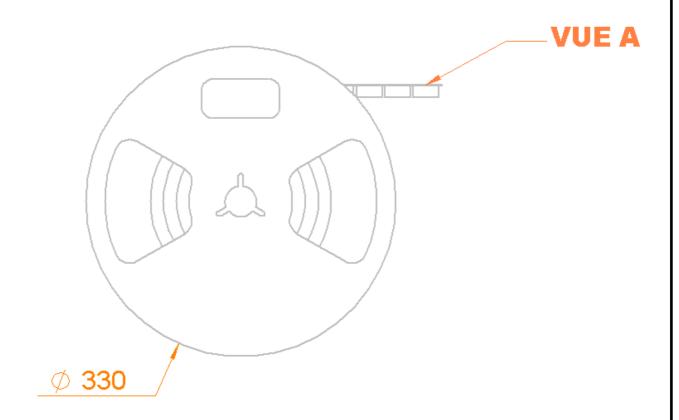
**Issue:** 1121 In the effort to improve our products, we reserve the right to make changes judged to be



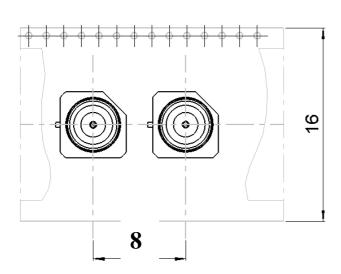
# FULL DETENT-TAPE AND REEL BY 500

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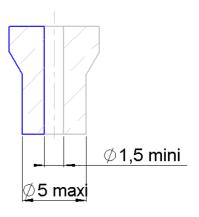
Series: SMP-COM



# Vue suivant A



# **AIR SUNCTION**



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